

Material Data Sheet

NTC

Termination

Solder

Leads

Composite

Heavy Metal

Heavy Metal

Product Class: Date		Inrush Cur B57xxxS*** B57127P50						
		30.09.2019						
IMDS ID if available								
Version:		5.03						
Product Part (IMDS: semi component)		Material Class (IMDS Material) (C		Substance	TMPS**) [wt%]	CAS if applicable	typical mass of material [wt-%]	Traces see 1)
Active Part	Ceramic		3B	Mn3O4 NiO CuO ZnO	60 20 10 5	1317-35-7 1313-99-1 1317-38-0 1314-13-2	63	

95

5

91

8

1 100 7440-22-4

7439-92-1

7440-31-5

7440-36-0

7440-50-8

1

6

21

	-											
	Heavy Metal		1C8		Sn		100		7440-31-5	1		
Encapsulation	Organic, solid		4B		SiO2 Silicone C.I. Pigment black 28 others*)		82,5 9 6 2,5		60676-86-0 67763-03-5 68186-91-4	8		
									Sum in total:	10	0	
sizes [mm]	weight range [g]	material numbers	size	es [mm]	weight range [g]	material numbers		sizes [n	nm] weight rang	e[g]	material	numbers
49 x 8.5 x 6	0.3 - 1.0	B57153S***V 9	50 3	x 9.5 x 6	0.6 - 1.3	B57235S***V 9		63 x 26	x 7 8.0 - 12.0		B57464S	5***V 9
54 x 15 x 7	1.6 - 3.3	B57234S***V 9	52 3	x 11.5 x 6	0.9 - 1.9	B57236S***V 9		60 x 21	x 7 3.0 - 5.6		B57364S	5***V 9
54 x 15 x 7	1.1 – 3.3	B57237S***V 9	55 3	x 16 x 7	2.0 - 4.1	B57238S***V 9		71 x 31	x 7 9.0 - 13.0		B57127F	2508* V 9
Not part of a Product Class												

not putt of								
Contact	Mr. Christoph Ronne	er	Important remarks:					
Division	PPD Q QM		1)	The declaration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906). Traces are				
Address	8530 Deutschlandst	berg, AUSTRIA		product parts, substances etc. that are below a percentage of 0.1 % by weight, if not otherwise regulated. This Material Data Sheet contains typical values of the respective products set forth				
	Tel: +43 3462 800 2139	mailto: functional.ppd-eqpm.db@tdk-electronics.tdk.com	m 2)					
*) others: .(not declarable or prohibited substances acc. GADSL)				herein. We expressly point out that all values and statements contained herein are based on our best present knowledge and cannot be regarded as binding statements				
**) typical m	ass percentage of subs	tance		or binding product specifications, unless otherwise explicitly agreed in writing. TDk				
+) listed in the Candidate list of Substances of Very High Concern acc. to				ELECTRONICS AG AND ITS AFFILIATES HEREBY EXPRESSLY DISCLAIM AN' REPRESENTATION OR WARRANTY. WHETHER EXPRESS. IMPLIED OR				
Regulation 1907/2006/EC				STATUTORY, WITH REGARD TO THE STATEMENTS AND VALUES CONTAINED HEREIN, INCLUDING BUT NOT LIMITED TO ANY REPRESENTATION OR				
				WARRANTY OF MERCHANTABILITY OR SUITABILITY FOR ANY PURPOSE.				

The products set forth herein are "RoHS-compatible". RoHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

RoHS - Exemptions for the Product Class / Product according to Annex III: (🗵 valid 🗆 not valid)

4D

1C15

1C12

Ag

Pb +)

Sn

Sb

Cu

Glass frit (boro-silicate)

□ no exemptions;

Exemption 6 (a): Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight;

Exemption 6 (b): Lead as an alloying element in aluminium containing up to 0,4 % lead by weight;

- Exemption 6 (c): Copper alloy containing up to 4 % lead by weight;
- Exemption 7 (a): Lead in high melting temperature type solder (i.e. lead-based alloys containing 85 % by weight or more lead);

Exemption 7 (c)-1: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound;

- Exemption 7 (c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher;
- Exemption 7 (c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC;

Exemption 15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages;

Other Exemption than above